

3.3GHz ÷ Fixed Modulus Divider

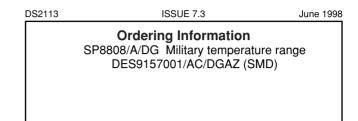
Advance Information

Features

- · Very High Speed Operation 3.3GHz
- Silicon Technology for low Phase Noise (Typically better than -140dBc/Hz at 10kHz)
- Specified Over the Full Military Temperature Range
- Low Power Dissipation 345mW (typ)
- 5V Single Supply Operation
- High Input Sensitivity
- · Very Wide Operating Frequency Range
- Available as DESC SMD 5962-9157001MPA

Description

The SP8808 is one of a range of very high speed low power prescalers for professional and military applications. The device features a complementary output stage with on chip current source for the emitter follower outputs.



Thermal Characteristics

 θ ja = 150°C/W θ jc = 50°C/W

Absolute Maximum Ratings

Supply voltage V_{CC} 6.5V Clock Input voltage 2.5V p-p Storage temperature range Junction temperature $+175^{\circ}C$

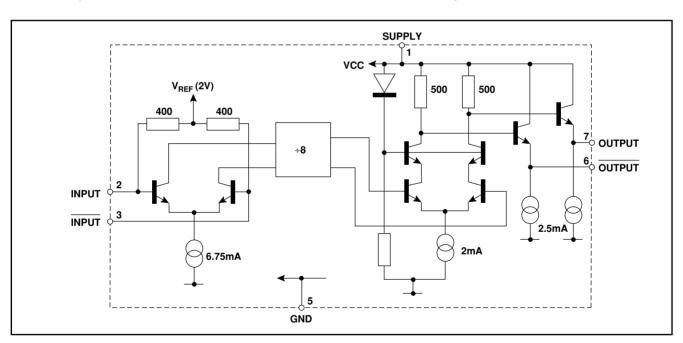


Figure 1 - SP8808 Block diagram

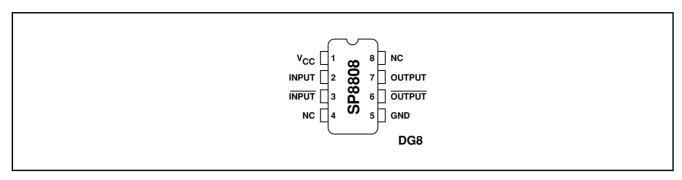


Figure 2 - Pin connections

Electrical Characteristics

Guaranteed over the temperature range T_{amb} -55°C to +125°C (see note) and supply voltage range 4.75V to 5.25V. Tested at T_{amb} = -55°C and +110°C, V_{CC} = 4.75V and 5.25V.

Characteristic		Value			Units	Conditions	
Characteristic	Pin	Min	Тур	Max	Ullits	Conditions	
Supply current Input sensitivity	1 2, 3		69	85	mA	V _{cc} = 5V RMS sinewave	
0.65GHz to 2.8GHz 3.3GHz				175 400	mV mV	measured in 50 ohm system. See Figs. 3 & 4	
Input impedance (series equivalent)	2, 3		50 2		Ω pF		
Output Voltage with $f_{in} = 1000MHz$ Output Voltage with $f_{in} = 3GHz$	6, 7 6, 7	0.8	1 0.4		Vp-p Vp-p	$V_{CC} = 5V$ $V_{CC} = 5V$ load as Fig. 4	

NOTE: Devices must be used with a suitable heatsink to maintain chip temperature below 175°C when operating at T_{amb} >110°C.

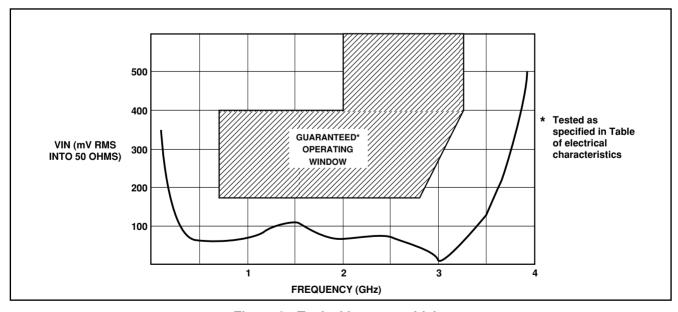


Figure 3 - Typical input sensitivity

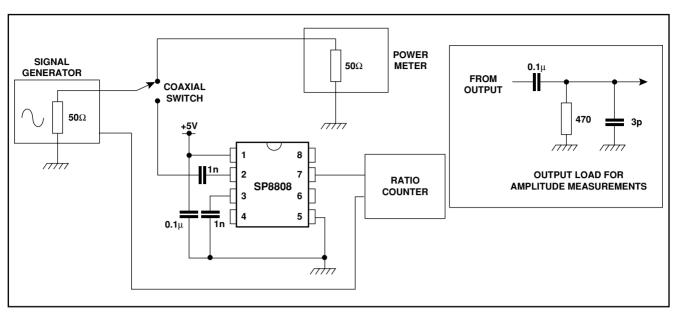


Figure 4 - Test circuit

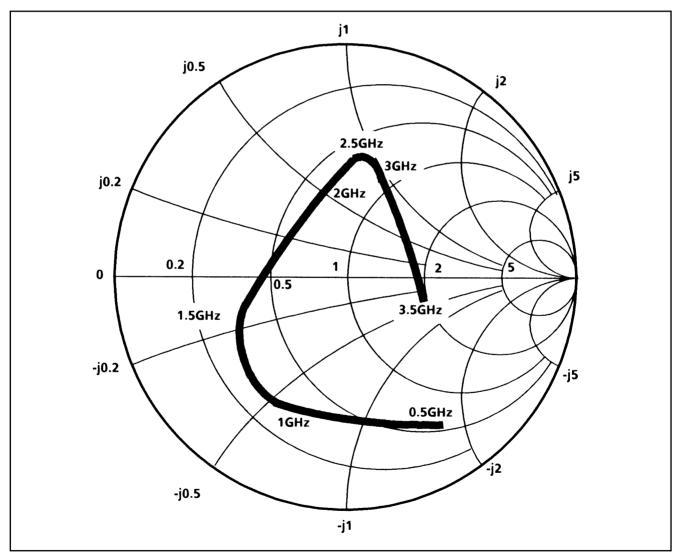
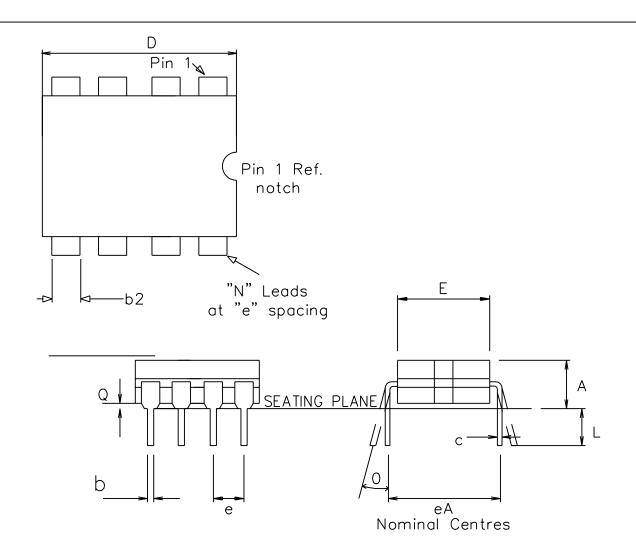


Figure 5 - Typical input impedance



	Alterr	n. Dimer	isions		Control Dimensions			
Symbol	in	millimet	res		in inches			
- ,		Nominal				Nominal		
L	3.18		4.06		0.125		0.160	
Α			5.08				0.200	
Q	0.51				0.020			
E	5.59		7.87		0.220		0.310	
eА		7.62				0.300		
С	0.20		0.36		0.008		0.014	
D			10.29				0.405	
е	2.54 BSC.				0.100 BSC.			
b2	1.14		1.65		0.045		0.065	
b	0.36		0.58		0.014		0.023	
0			15				15	
	Pin features							
N	8							
ND	4							
NE	0							
NOTE	RECTANGULAR							

This drawing supersedes 418/ED/39501/001 (Swindon)

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